

## Automatic IC Module Implanting Machine

Model: ICI-3000

### Purposes:

The strip module prepared with glue, punch and implant onto the milled IC card and dual-interface card base.

### Advantages:

1. PLC program control. Chinese/English touch screen and operation.
2. Integration of module tape gluing, module punching, module implanting and testing.



### Features:

1. Double card magazines to load/unload cards.
2. Automatically check card cavity and implant modules.
3. Equipped with dual-interface card coil on-off detection function, bad cards are rejected into the waste card box.
4. Spot weld for positioning, hot weld stations A & B, then cold lamination.
5. ATR detection after encapsulation, and automatically removes defective cards.
6. Automatically identify damaged modules, which can be identified and thrown into the waste box.
7. For different module, flexible replacement of glue preparing and punching module.

### Specifications:

Item	Details	Item	Details
Max. Speed	3000UPH	Suitable material	ISO7816 standard card of PVC, ABS, PET-G
Milling accuracy	X, Y = $\pm 0.015\text{mm}$	Temperature	100 °C ~ 300 °C (adjustable)
Implanting pressure	3 ~ 6Kg/cm <sup>2</sup>	Weight	1200kg
Power	AC220V, 50/60Hz, 1.5KW	Dimension	(L)1960mm x (W)800mm x (H)2050mm
Air consumption	250L/min	Environment	Constant temperature 22 °C, $\pm 3$ °C, dry and dust free.

**Notes:** above specification is subject to change without prior notice due to continuous improvement.